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## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPROP.
THM	5,744,192	04-28-98	Nguyen et al.	427	99	11-08-96

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY/NAME	CLASS	SUB CLASS	TRANSLATION YES NO

## OTHER DOCUMENTS

THM	Article by Gelatos et al., entitled "Chemical Vapor Deposition of Copper from Cu+1 Precursors in the Presence of Water Vapor", published in Appl. Phys. Lett. 63(20), 1993, pp. 2842-2844.
I	Article by Norman, et al., entitled "Chemical Additives For Improved Copper CVD Processing", published in Thin Solid Films 262 (1995) pp. 46-51, 1994.
THM	Article by Jain et al., entitled "Chemical Vapor Deposition of Copper from (hfac)CuL(L = tmvs and 2-butyne) in the Presence of Water, Methanol and Dimethyl Ether", published in Chem. Mater., 8, pp. 1119-1127, 1996.
EXAMINER	DATE CONSIDERED
FC	5/27/03